

AMENDMENTS TO THE CLAIMS

1-25. (Cancelled)

26. (Currently Amended) An electronic component to be mounted on a printed board, said electronic component comprising:

an electrical connecting surface;

~~a plurality of electrical connecting portions lands~~ provided on said electrical connecting surface in arrangement positions within a contour of said electronic component; and at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said ~~electrical connecting portions lands~~,

wherein said at least one recognition mark is formed on said surface simultaneously with formation of said lands on said electrical connecting surface.

27. (Currently Amended) The An-electronic component as claimed in claim 26, wherein said at least one recognition mark comprises a pair of recognition marks positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said ~~electrical connecting portions lands~~ are disposed in an array that surrounds said pair of recognition marks.

28. (Currently Amended) The An-electronic component as claimed in claim 26, wherein said at least one recognition mark comprises plural ~~a plurality of~~ recognition marks that are positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said plural recognition marks are located in a central portion of said electrical connecting surface, and said ~~electrical connecting portions lands~~ are disposed around said plural recognition marks.

29. (Currently Amended) The An-electronic component as claimed in claim 26, wherein said at least one recognition mark is provided on a side of said electrical connecting surface that is adapted to confront a mounting position of the printed board.

30. (Currently Amended) The An-electronic component as claimed in claim 29, wherein said at least one recognition mark comprises a projection or a printed symbol.

31. (Currently Amended) An electronic component to be mounted on a printed board, said electronic component comprising:

an electrical connecting surface;

a plurality of electrical connecting portions provided on said electrical connecting surface in arrangement positions; and

at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said electrical connecting portions,

wherein said at least one recognition mark includes coded information indicative of said electronic component.

32. (Currently Amended) The An electronic component as claimed in claim 31, wherein the coded information of said at least one recognition mark is information concerned with a state in which the electrical connecting portions are formed.

33. (Currently Amended) The An electronic component as claimed in claim 26, wherein said at least one recognition mark is located in a corner portion of an opposite side of the electronic component relative to said electrical connecting portions lands.

34. (Cancelled)

35. (Currently Amended) The An electronic component as claimed in claim 26 31, wherein said electrical connecting portions are solder bumps.

36. (Currently Amended) The An electronic component as claimed in claim 26 31, wherein said electrical connecting portions are lands.

37-47. (Cancelled)

48. (Currently Amended) The An electronic component as claimed in claim 26, wherein said at least one the-recognition mark does not project from the said surface of the electronic

component.

49. (New) The electronic component as claimed in claim 26, wherein said surface is said electrical connecting surface.

50. (New) The electronic component as claimed in claim 49, wherein said at least one recognition mark and said lands are formed simultaneously on said electrical connecting surface by using a mask.

51. (New) The electronic component as claimed in claim 26, further comprising a solder bump on each of said lands.

52. (New) The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises a pair of recognition marks positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said lands are disposed in an array that surrounds said pair of recognition marks.

53. (New) The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises plural recognition marks that are positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said plural recognition marks are located in a central portion of said electrical connecting surface, and said lands are disposed around said plural recognition marks.

54. (New) The electronic component as claimed in claim 51, wherein said at least one recognition mark is provided on a side of said electrical connecting surface that is adapted to confront a mounting position of the printed board.

55. (New) The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises a projection or a printed symbol.

56. (New) The electronic component as claimed in claim 51, wherein said at least one

recognition mark does not project from said electrical connecting surface of the electronic component.

57. (New) The electronic component as claimed in claim 51, wherein said surface is said electrical connecting surface.

58. (New) The electronic component as claimed in claim 51, wherein said at least one recognition mark and said lands are formed simultaneously on said electrical connecting surface by using a mask.